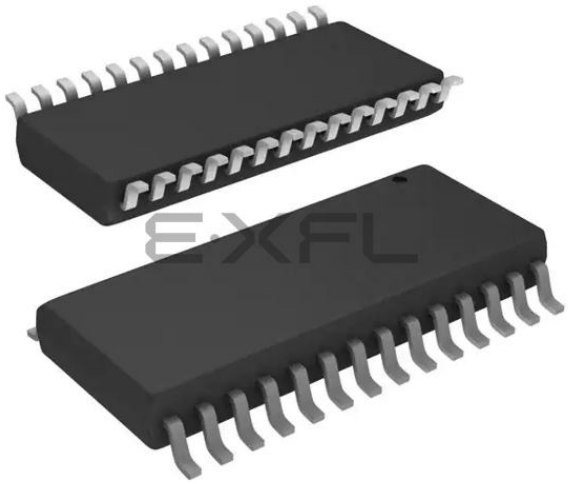
Microchip Technology - DSPIC33EV256GM002-I/SO Datasheet



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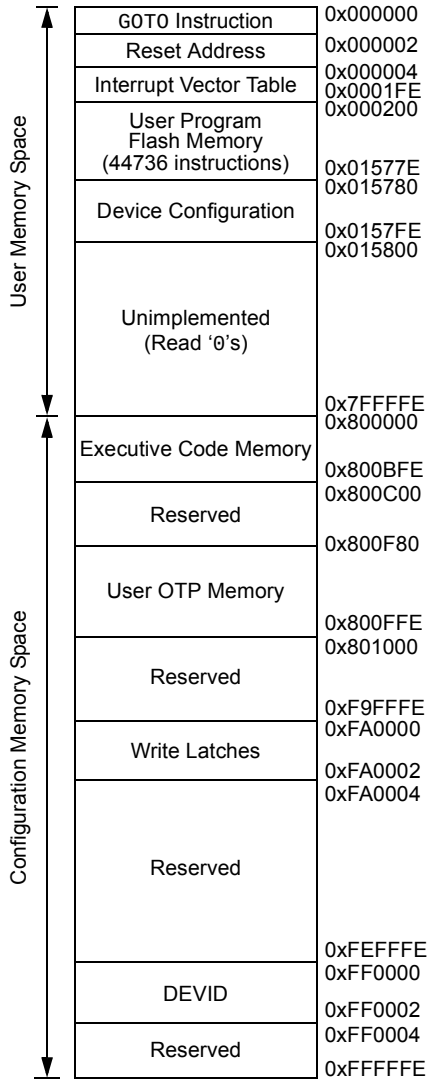
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 11x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev256gm002-i-so

FIGURE 4-3: PROGRAM MEMORY MAP FOR dsPIC33EV128GM00X/10X DEVICES(1)



Note 1: Memory areas are not shown to scale.

4.2.5 X AND Y DATA SPACES

The dsPIC33EVXXXGM00X/10X family core has two Data Spaces: X and Y. These Data Spaces can be considered either separate (for some DSP instructions) or as one unified, linear address range (for MCU instructions). The Data Spaces are accessed using two Address Generation Units (AGUs) and separate data paths. This feature allows certain instructions to concurrently fetch two words from RAM, thereby enabling efficient execution of DSP algorithms, such as Finite Impulse Response (FIR) filtering and Fast Fourier Transform (FFT).

The X DS is used by all instructions and supports all addressing modes. The X DS has separate read and write data buses. The X read data bus is the read data path for all instructions that view the DS as combined X and Y address space. It is also the X data prefetch path for the dual operand DSP instructions (MAC class).

The Y DS is used in concert with the X DS by the MAC class of instructions (CLR, ED, EDAC, MAC, MOVSAC, MPY, MPY.N and MSC) to provide two concurrent data read paths.

Both the X and Y Data Spaces support Modulo Addressing mode for all instructions, subject to addressing mode restrictions. Bit-Reversed Addressing mode is only supported for writes to the X Data Space.

All data memory writes, including in DSP instructions, view Data Space as combined X and Y address space. The boundary between the X and Y Data Spaces is device-dependent and is not user-programmable.

REGISTER 14-5: DMTCNTL: DEADMAN TIMER COUNT REGISTER LOW

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
COUNTER<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
COUNTER<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **COUNTER<15:0>:** Read Current Contents of Lower DMT Counter bits

REGISTER 14-6: DMTCNTH: DEADMAN TIMER COUNT REGISTER HIGH

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
COUNTER<31:24>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
COUNTER<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **COUNTER<31:16>:** Read Current Contents of Higher DMT Counter bits

REGISTER 17-12: TRGCONx: PWMx TRIGGER CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
TRGDIV3	TRGDIV2	TRGDIV1	TRGDIV0	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	TRGSTRT5(1)	TRGSTRT4(1)	TRGSTRT3(1)	TRGSTRT2(1)	TRGSTRT1(1)	TRGSTRT0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **TRGDIV<3:0>:** Trigger Output Divider bits

1111 = Triggers output for every 16th trigger event
1110 = Triggers output for every 15th trigger event
1101 = Triggers output for every 14th trigger event
1100 = Triggers output for every 13th trigger event
1011 = Triggers output for every 12th trigger event
1010 = Triggers output for every 11th trigger event
1001 = Triggers output for every 10th trigger event
1000 = Triggers output for every 9th trigger event
0111 = Triggers output for every 8th trigger event
0110 = Triggers output for every 7th trigger event
0101 = Triggers output for every 6th trigger event
0100 = Triggers output for every 5th trigger event
0011 = Triggers output for every 4th trigger event
0010 = Triggers output for every 3rd trigger event
0001 = Triggers output for every 2nd trigger event
0000 = Triggers output for every trigger event

bit 11-6 **Unimplemented:** Read as '0'

bit 5-0 **TRGSTRT<5:0>:** Trigger Postscaler Start Enable Select bits(1)

111111 = Waits 63 PWM cycles before generating the first trigger event after the module is enabled
•
•
•
000010 = Waits 2 PWM cycles before generating the first trigger event after the module is enabled
000001 = Waits 1 PWM cycle before generating the first trigger event after the module is enabled
000000 = Waits 0 PWM cycles before generating the first trigger event after the module is enabled

Note 1: The secondary PWM generator cannot generate PWMx trigger interrupts.

REGISTER 17-15: FCLCONx: PWMx FAULT CURRENT-LIMIT CONTROL REGISTER(1) (CONTINUED)

bit 7-3 **FLTSRC<4:0>:** Fault Control Signal Source Select for PWM Generator x bits
11111 = Fault 32 **(default)**
11110 = Reserved
•
•
•
01100 = Op Amp/Comparator 5
01011 = Comparator 4
01010 = Op Amp/Comparator 3
01001 = Op Amp/Comparator 2
01000 = Op Amp/Comparator 1
00111 = Fault 8
00110 = Fault 7
00101 = Fault 6
00100 = Fault 5
00011 = Fault 4
00010 = Fault 3
00001 = Fault 2
00000 = Fault 1

bit 2 **FLTPOL:** Fault Polarity for PWM Generator x bit(2)
1 = The selected Fault source is active-low
0 = The selected Fault source is active-high

bit 1-0 **FLTMOD<1:0>:** Fault Mode for PWM Generator x bits
11 = Fault input is disabled
10 = Reserved
01 = The selected Fault source forces the PWMxH, PWMxL pins to FLTDAT<1:0> values (cycle)
00 = The selected Fault source forces the PWMxH, PWMxL pins to FLTDAT<1:0> values (latched condition)

Note 1: If the PWMLOCK Configuration bit (FDEVOPT<0>) is a '1', the FCLCONx register can only be written after the unlock sequence has been executed.

2: These bits should be changed only when PTEN = 0. Changing the clock selection during operation will yield unpredictable results.

REGISTER 17-16: LEBCONx: PWMx LEADING-EDGE BLANKING CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	BCH(1)	BCL(1)	BPHH	BPHL	BPLH	BPLL
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **PHR:** PWMxH Rising Edge Trigger Enable bit
1 = Rising edge of PWMxH will trigger the Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores the rising edge of PWMxH

bit 14 **PHF:** PWMxH Falling Edge Trigger Enable bit
1 = Falling edge of PWMxH will trigger the Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores the falling edge of PWMxH

bit 13 **PLR:** PWMxL Rising Edge Trigger Enable bit
1 = Rising edge of PWMxL will trigger the Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores the rising edge of PWMxL

bit 12 **PLF:** PWMxL Falling Edge Trigger Enable bit
1 = Falling edge of PWMxL will trigger the Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores the falling edge of PWMxL

bit 11 **FLTLEBEN:** Fault Input Leading-Edge Blanking Enable bit
1 = Leading-Edge Blanking is applied to the selected Fault input
0 = Leading-Edge Blanking is not applied to the selected Fault input

bit 10 **CLLEBEN:** Current-Limit Input Leading-Edge Blanking Enable bit
1 = Leading-Edge Blanking is applied to the selected current-limit input
0 = Leading-Edge Blanking is not applied to the selected current-limit input

bit 9-6 **Unimplemented:** Read as '0'

bit 5 **BCH:** Blanking in Selected Blanking Signal High Enable bit(1)
1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is high
0 = No blanking when the selected blanking signal is high

bit 4 **BCL:** Blanking in Selected Blanking Signal Low Enable bit(1)
1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is low
0 = No blanking when the selected blanking signal is low

bit 3 **BPHH:** Blanking in PWMxH High Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when the PWMxH output is high
0 = No blanking when the PWMxH output is high

bit 2 **BPHL:** Blanking in PWMxH Low Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when the PWMxH output is low
0 = No blanking when the PWMxH output is low

bit 1 **BPLH:** Blanking in PWMxL High Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when the PWMxL output is high
0 = No blanking when the PWMxL output is high

bit 0 **BPLL:** Blanking in PWMxL Low Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when the PWMxL output is low
0 = No blanking when the PWMxL output is low

Note 1: The blanking signal is selected through the BLANKSEL<3:0> bits in the AUXCONx register.

NOTES:

REGISTER 18-2: SPIxCON1: SPIx CONTROL REGISTER 1

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	DISSCK	DISSDO	MODE16	SMP	CKE(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SSEN(2)	CKP	MSTEN	SPRE2(3)	SPRE1(3)	SPRE0(3)	PPRE1(3)	PPRE0(3)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12 **DISSCK:** Disable SCKx Pin bit (SPI Master modes only)
1 = Internal SPI clock is disabled, pin functions as I/O
0 = Internal SPI clock is enabled

bit 11 **DISSDO:** Disable SDOx Pin bit
1 = SDOx pin is not used by the module; pin functions as I/O
0 = SDOx pin is controlled by the module

bit 10 **MODE16:** Word/Byte Communication Select bit
1 = Communication is word-wide (16 bits)
0 = Communication is byte-wide (8 bits)

bit 9 **SMP:** SPIx Data Input Sample Phase bit
Master mode:
1 = Input data is sampled at the end of data output time
0 = Input data is sampled at the middle of data output time
Slave mode:
SMP must be cleared when SPIx is used in Slave mode.

bit 8 **CKE:** Clock Edge Select bit(1)
1 = Serial output data changes on transition from active clock state to Idle clock state (refer to bit 6)
0 = Serial output data changes on transition from Idle clock state to active clock state (refer to bit 6)

bit 7 **SSEN:** Slave Select Enable bit (Slave mode)(2)
1 = $\overline{SSx}$ pin is used for Slave mode
0 = $\overline{SSx}$ pin is not used by the module; pin is controlled by port function

bit 6 **CKP:** Clock Polarity Select bit
1 = Idle state for clock is a high level; active state is a low level
0 = Idle state for clock is a low level; active state is a high level

bit 5 **MSTEN:** Master Mode Enable bit
1 = Master mode
0 = Slave mode

Note 1: The CKE bit is not used in Framed SPI modes. Program this bit to '0' for Framed SPI modes (FRMEN = 1).
2: This bit must be cleared when FRMEN = 1.
3: Do not set both primary and secondary prescalers to the value of 1:1.

21.2 UART Control Registers

REGISTER 21-1: UxMODE: UARTx MODE REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
UARTEN(1)	—	USIDL	IREN(2)	RTSMD	—	UEN1	UEN0
bit 15							bit 8

R/W-0, HC	R/W-0	R/W-0, HC	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
WAKE	LPBACK	ABAUD	URXINV	BRGH	PDSEL1	PDSEL0	STSEL
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **UARTEN:** UARTx Enable bit(1)
- 1 = UARTx is enabled; all UARTx pins are controlled by UARTx as defined by UEN<1:0>
- 0 = UARTx is disabled; all UARTx pins are controlled by PORT latches; UARTx power consumption is minimal

bit 14 **Unimplemented:** Read as '0'

bit 13 **USIDL:** UARTx Stop in Idle Mode bit
- 1 = Discontinues module operation when the device enters Idle mode
- 0 = Continues module operation in Idle mode

bit 12 **IREN:** IrDA® Encoder and Decoder Enable bit(2)
- 1 = IrDA encoder and decoder are enabled
- 0 = IrDA encoder and decoder are disabled

bit 11 **RTSMD:** Mode Selection for $\overline{\text{UxRTS}}$ Pin bit
- 1 = $\overline{\text{UxRTS}}$ pin is in Simplex mode
- 0 = $\overline{\text{UxRTS}}$ pin is in Flow Control mode

bit 10 **Unimplemented:** Read as '0'

bit 9-8 **UEN<1:0>:** UARTx Pin Enable bits
- 11 = UxTX, UxRX and BCLKx pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by PORT latches(3)
- 10 = UxTX, UxRX, $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins are enabled and used(4)
- 01 = UxTX, UxRX and $\overline{\text{UxRTS}}$ pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by PORT latches(4)
- 00 = UxTX and UxRX pins are enabled and used; $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$/BCLKx pins are controlled by PORT latches

bit 7 **WAKE:** UARTx Wake-up on Start bit Detect During Sleep Mode Enable bit
- 1 = UARTx continues to sample the UxRX pin; interrupt is generated on the falling edge, bit is cleared in hardware on the following rising edge
- 0 = Wake-up is not enabled

bit 6 **LPBACK:** UARTx Loopback Mode Select bit
- 1 = Loopback mode is enabled
- 0 = Loopback mode is disabled

Note 1: Refer to **"Universal Asynchronous Receiver Transmitter (UART)"** (DS70000582) in the *"dsPIC33/PIC24 Family Reference Manual"* for information on enabling the UART module for receive or transmit operation.

2: This feature is only available for the 16x BRG mode (BRGH = 0).

3: This feature is only available on 44-pin and 64-pin devices.

4: This feature is only available on 64-pin devices.

24.2 ADC Helpful Tips

1. The SMPIx control bits in the ADxCON2 registers:
   a) Determine when the ADC interrupt flag is set and an interrupt is generated, if enabled.
   b) When the CSCNA bit in the ADxCON2 register is set to '1', this determines when the ADC analog scan channel list, defined in the ADxCSSL/ADxCSSH registers, starts over from the beginning.
   c) When the DMA peripheral is not used (ADDMAEN = 0), this determines when the ADC Result Buffer Pointer to ADC1BUF0-ADC1BUFF gets reset back to the beginning at ADC1BUF0.
   d) When the DMA peripheral is used (ADDMAEN = 1), this determines when the DMA Address Pointer is incremented after a sample/conversion operation. ADC1BUF0 is the only ADC buffer used in this mode. The ADC Result Buffer Pointer to ADC1BUF0-ADC1BUFF gets reset back to the beginning at ADC1BUF0. The DMA address is incremented after completion of every 32nd sample/conversion operation. Conversion results are stored in the ADC1BUF0 register for transfer to RAM using the DMA peripheral.
2. When the DMA module is disabled (ADDMAEN = 0), the ADC has 16 result buffers. ADC conversion results are stored sequentially in ADC1BUF0-ADC1BUFF, regardless of which analog inputs are being used subject to the SMPIx bits and the condition described in 1.c) above. There is no relationship between the ANx input being measured and which ADC buffer (ADC1BUF0-ADC1BUFF) that the conversion results will be placed in.
3. When the DMA module is enabled (ADDMAEN = 1), the ADC module has only 1 ADC result buffer (i.e., ADCxBUF0) per ADC peripheral and the ADC conversion result must be read, either by the CPU or DMA Controller, before the next ADC conversion is complete to avoid overwriting the previous value.
4. The DONE bit (ADxCON1<0>) is only cleared at the start of each conversion and is set at the completion of the conversion, but remains set indefinitely, even through the next sample phase until the next conversion begins. If application code is monitoring the DONE bit in any kind of software loop, the user must consider this behavior because the CPU code execution is faster than the ADC. As a result, in Manual Sample mode, particularly where the user's code is setting the SAMP bit (ADxCON1<1>), the DONE bit should also be cleared by the user application just before setting the SAMP bit.
5. Enabling op amps, comparator inputs and external voltage references can limit the availability of analog inputs (ANx pins). For example, when Op Amp 2 is enabled, the pins for AN0, AN1 and AN2 are used by the op amp's inputs and output. This negates the usefulness of Alternate Input mode since the MUX A selections use AN0-AN2. Carefully study the ADC block diagram to determine the configuration that will best suit your application. For configuration examples, refer to **"Analog-to-Digital Converter (ADC)"** (DS70621) in the *"dsPIC33/PIC24 Family Reference Manual"*.

REGISTER 25-2: CMxCON: COMPARATOR x CONTROL REGISTER (x = 1, 2, 3 OR 5) (CONTINUED)

bit 7-6 **EVPOL<1:0>:** Trigger/Event/Interrupt Polarity Select bits(3)

11 = Trigger/event/interrupt generated on any change of the comparator output (while CEVT = 0)

10 = Trigger/event/interrupt generated only on high-to-low transition of the polarity selected comparator output (while CEVT = 0)

If CPOL = 1 (inverted polarity):
Low-to-high transition of the comparator output.

If CPOL = 0 (non-inverted polarity):
High-to-low transition of the comparator output.

01 = Trigger/event/interrupt generated only on low-to-high transition of the polarity selected comparator output (while CEVT = 0)

If CPOL = 1 (inverted polarity):
High-to-low transition of the comparator output.

If CPOL = 0 (non-inverted polarity):
Low-to-high transition of the comparator output.

00 = Trigger/event/interrupt generation is disabled

bit 5 **Unimplemented:** Read as '0'

bit 4 **CREF:** Comparator x Reference Select bit (VIN+ input)(1)

1 = VIN+ input connects to the internal CVREFIN voltage
0 = VIN+ input connects to the CxIN1+ pin

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **CCH<1:0>:** Op Amp/Comparator x Channel Select bits(1)

11 = Inverting input of op amp/comparator connects to the CxIN4- pin
10 = Inverting input of op amp/comparator connects to the CxIN3- pin
01 = Inverting input of op amp/comparator connects to the CxIN2- pin
00 = Inverting input of op amp/comparator connects to the CxIN1- pin

Note 1: Inputs that are selected and not available will be tied to VSS. See the **"Pin Diagrams"** section for available inputs for each package.

2: The op amp and the comparator can be used simultaneously in these devices. The OPAEN bit only enables the op amp while the comparator is still functional.

3: After configuring the comparator, either for a high-to-low or low-to-high COUT transition (EVPOL<1:0> (CMxCON<7:6>) = 10 or 01), the Comparator x Event bit, CEVT (CMxCON<9>), and the Comparator Interrupt Flag, CMPIF (IFS1<2>), must be cleared before enabling the Comparator Interrupt Enable bit, CMPIE (IEC1<2>).

REGISTER 25-6: CMxFLTR: COMPARATOR x FILTER CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	CFSEL2	CFSEL1	CFSEL0	CFLTREN	CFDIV2	CFDIV1	CFDIV0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as '0'

bit 6-4 **CFSEL<2:0>:** Comparator x Filter Input Clock Select bits
111 = T5CLK(1)
110 = T4CLK(2)
101 = T3CLK(1)
100 = T2CLK(2)
011 = Reserved
010 = SYNCO1(3)
001 = FOSC(4)
000 = FP(4)

bit 3 **CFLTREN:** Comparator x Filter Enable bit
1 = Digital filter is enabled
0 = Digital filter is disabled

bit 2-0 **CFDIV<2:0>:** Comparator x Filter Clock Divide Select bits
111 = Clock divide 1:128
110 = Clock divide 1:64
101 = Clock divide 1:32
100 = Clock divide 1:16
011 = Clock divide 1:8
010 = Clock divide 1:4
001 = Clock divide 1:2
000 = Clock divide 1:1

Note 1: See the Type C Timer Block Diagram (Figure 13-2).
2: See the Type B Timer Block Diagram (Figure 13-1).
3: See the High-Speed PWMx Module Register Interconnection Diagram (Figure 17-2).
4: See the Oscillator System Diagram (Figure 9-1).

30.2 AC Characteristics and Timing Parameters

This section defines the dsPIC33EVXXXGM00X/10X family AC characteristics and timing parameters.

TABLE 30-15: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended Operating voltage VDD range as described in **Section 30.1 "DC Characteristics"**.

FIGURE 30-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

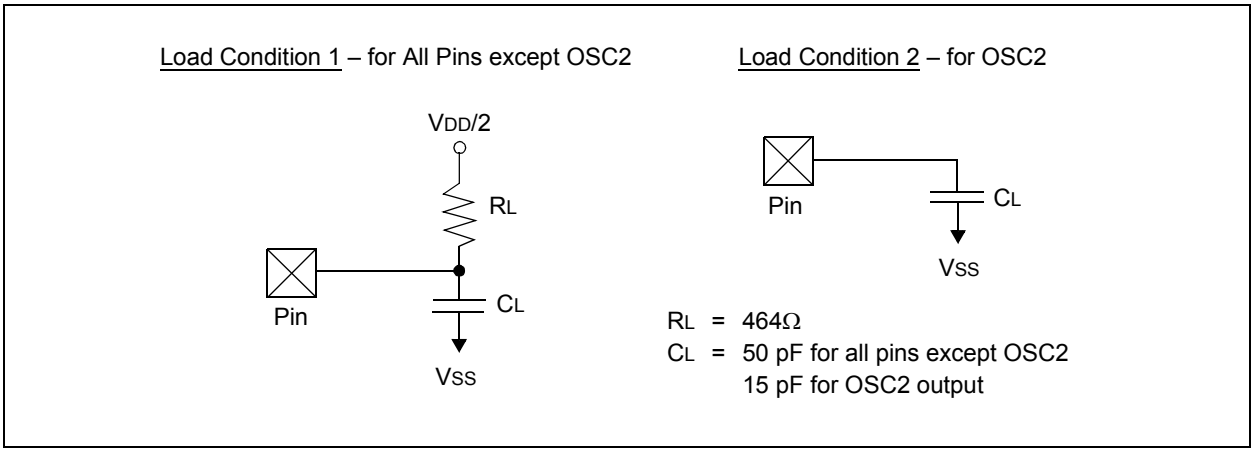
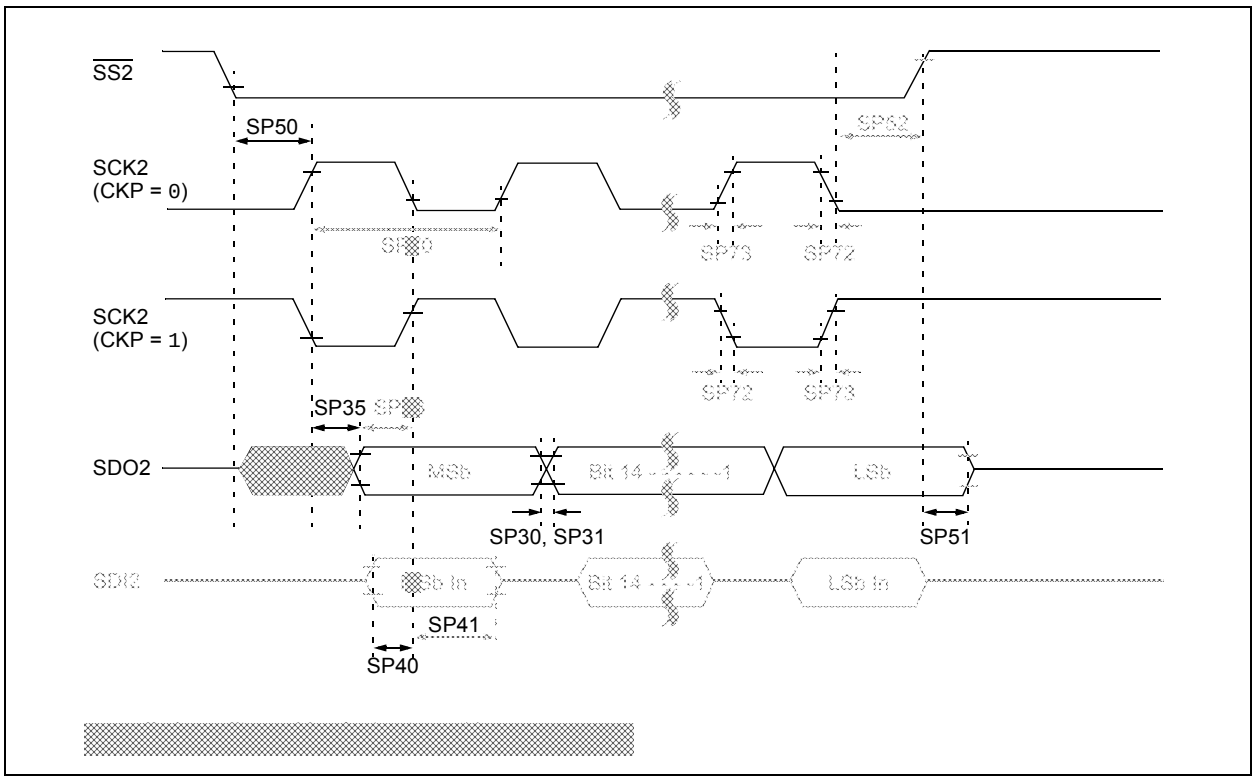


TABLE 30-16: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
DO50	COSCO	OSC2 Pin	—	—	15	pF	In XT and HS modes, when external clock is used to drive OSC1
DO56	CIO	All I/O Pins and OSC2	—	—	50	pF	EC mode
DO58	CB	SCLx, SDAx	—	—	400	pF	In I^2C mode

FIGURE 30-19: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING CHARACTERISTICS



31.0 HIGH-TEMPERATURE ELECTRICAL CHARACTERISTICS

This section provides an overview of the dsPIC33EVXXXGM00X/10X family electrical characteristics for devices operating in an ambient temperature range of -40°C to +150°C.

The specifications between -40°C to +150°C are identical to those shown in **Section 30.0 "Electrical Characteristics"** for operation between -40°C to +125°C, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, Parameter DC10 in **Section 30.0 "Electrical Characteristics"** is the Industrial and Extended temperature equivalent of HDC10.

Absolute maximum ratings for the dsPIC33EVXXXGM00X/10X family high-temperature devices are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these, or any other conditions above the parameters indicated in the operation listings of this specification, is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias(2) ..... -40°C to +150°C
Storage temperature ..... -65°C to +160°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +6.0V
Maximum current out of V_{SS} pin ..... 350 mA
Maximum current into V_{DD} pin(3) ..... 350 mA
Maximum junction temperature ..... +155°C
Maximum current sunk by any I/O pin ..... 20 mA
Maximum current sourced by I/O pin ..... 18 mA
Maximum current sunk by all ports combined ..... 200 mA
Maximum current sourced by all ports combined(3) ..... 200 mA

Note 1: Stresses above those listed under "Absolute Maximum Ratings" can cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.

2: AEC-Q100 reliability testing for devices intended to operate at +150°C is 1,000 hours. Any design in which the total operating time from +125°C to +150°C will be greater than 1,000 hours is not warranted without prior written approval from Microchip Technology Inc.

3: Maximum allowable current is a function of device maximum power dissipation (see Table 31-2).

TABLE 31-16: CTMU CURRENT SOURCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
CTMU Current Source							
HCTMUI1	IOUT1	Base Range	—	550	—	nA	CTMUICON<9.8> = 01
HCTMUI2	IOUT2	10x Range	—	5.5	—	μA	CTMUICON<9.8> = 10
HCTMUI3	IOUT3	100x Range	—	55	—	μA	CTMUICON<9.8> = 11
HCTMUI0	IOUT4	1000x Range	—	550	—	μA	CTMUICON<9.8> = 00
HCTMUFV1	VF	Temperature Diode Forward Voltage(2)	—	0.525	—	V	TA = +25°C, CTMUICON<9.8> = 01
			—	0.585	—	V	TA = +25°C, CTMUICON<9.8> = 10
			—	0.645	—	V	TA = +25°C, CTMUICON<9.8> = 11

Note 1: Normal value at center point of current trim range (CTMUICON<15:10> = 000000).

2: Parameters are characterized but not tested in manufacturing. Measurements are taken with the following conditions:

- VREF = AVDD = 5.0V
- ADC module configured for 10-bit mode
- ADC module configured for conversion speed of 500 ksps
- All PMDx bits are cleared (PMDx = 0)
- CPU executing

```
while(1)
{
NOP();
}
```

- Device operating from the FRC with no PLL

FIGURE 32-3: TYPICAL IDD vs. VDD (EC MODE, 20 MIPS)

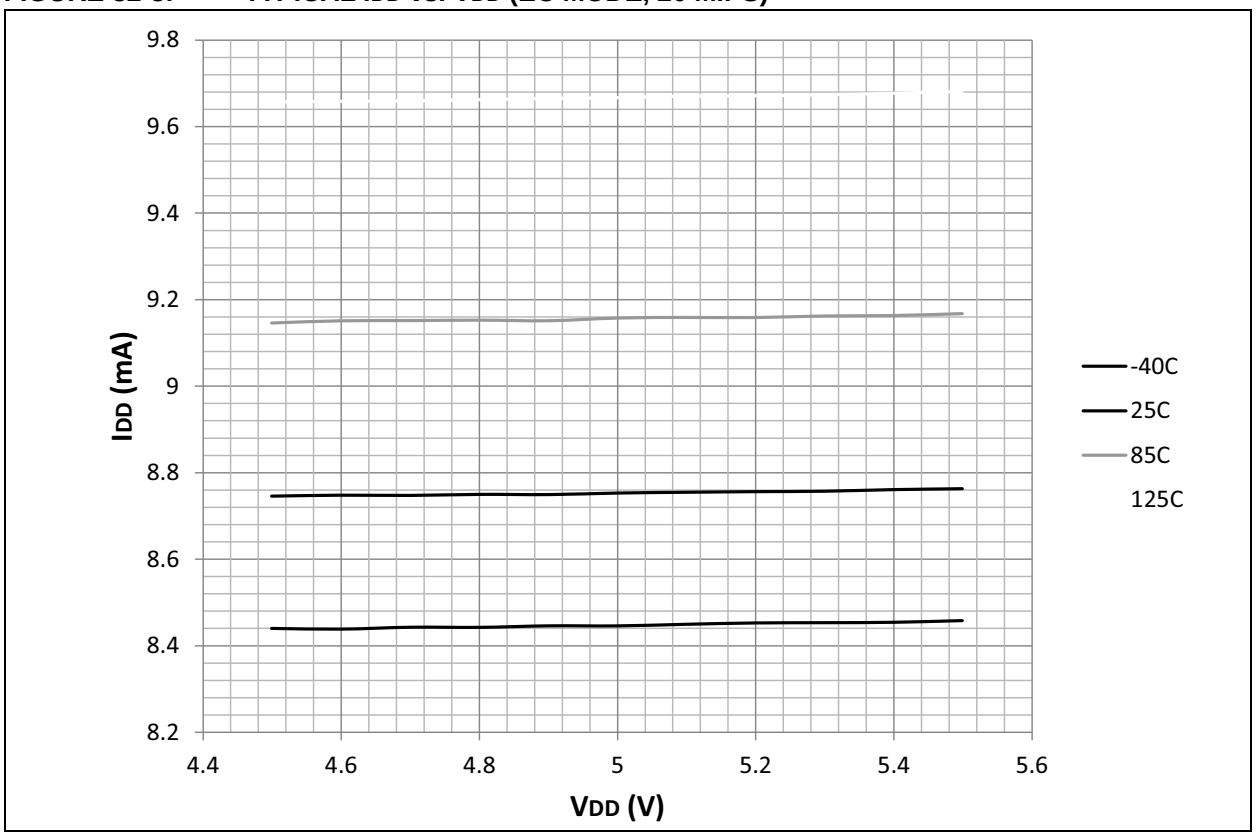


FIGURE 32-4: TYPICAL IDD vs. VDD (EC MODE, 40 MIPS)

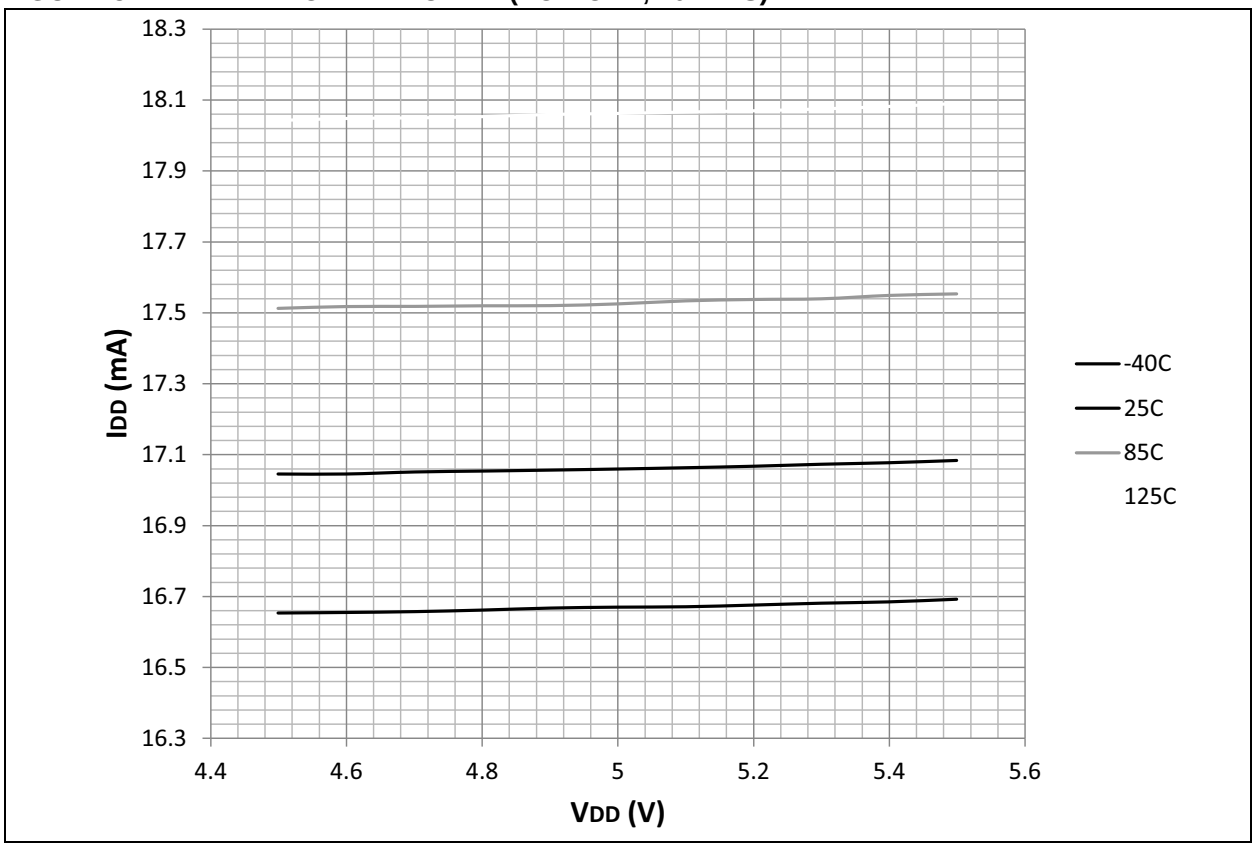


FIGURE 33-11: TYPICAL IDOZE VS. VDD (DOZE 1:128, 70 MIPS)

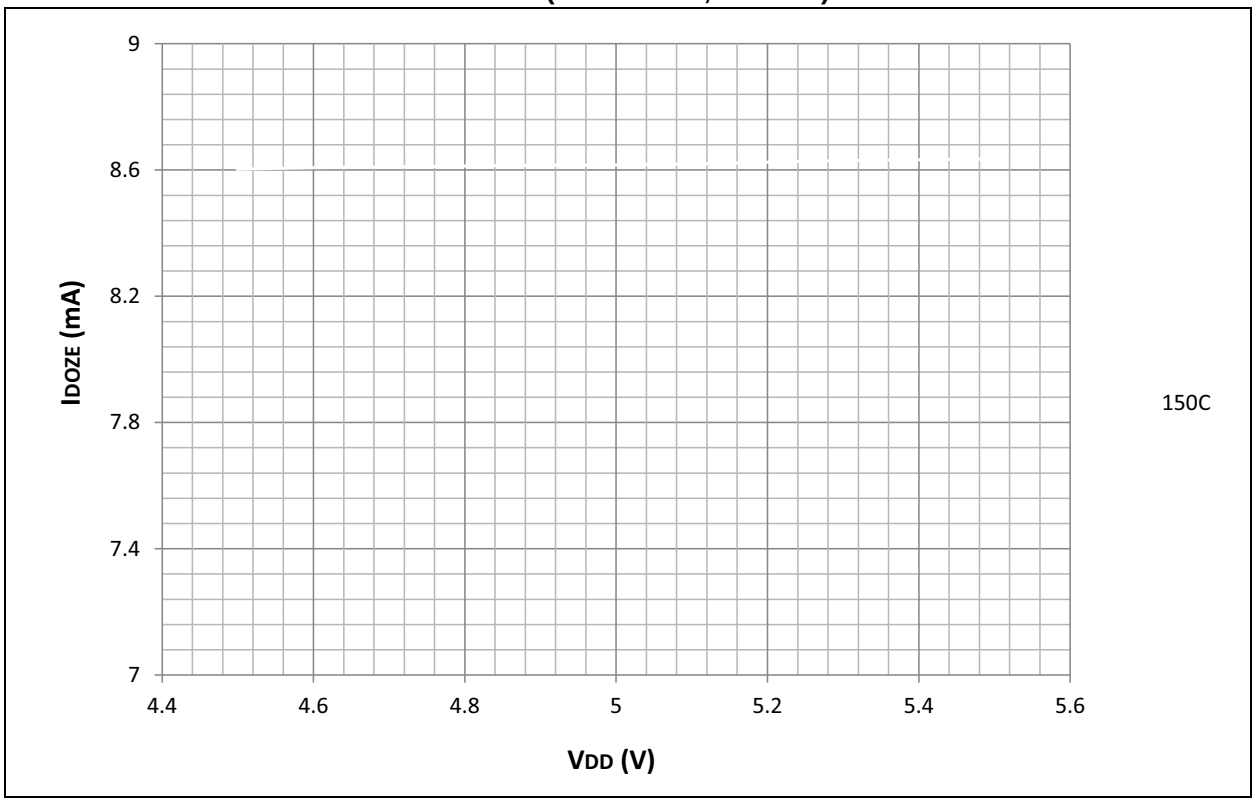


FIGURE 33-12: TYPICAL/MAXIMUM IDOZE VS. TEMPERATURE (DOZE 1:128, 70 MIPS)

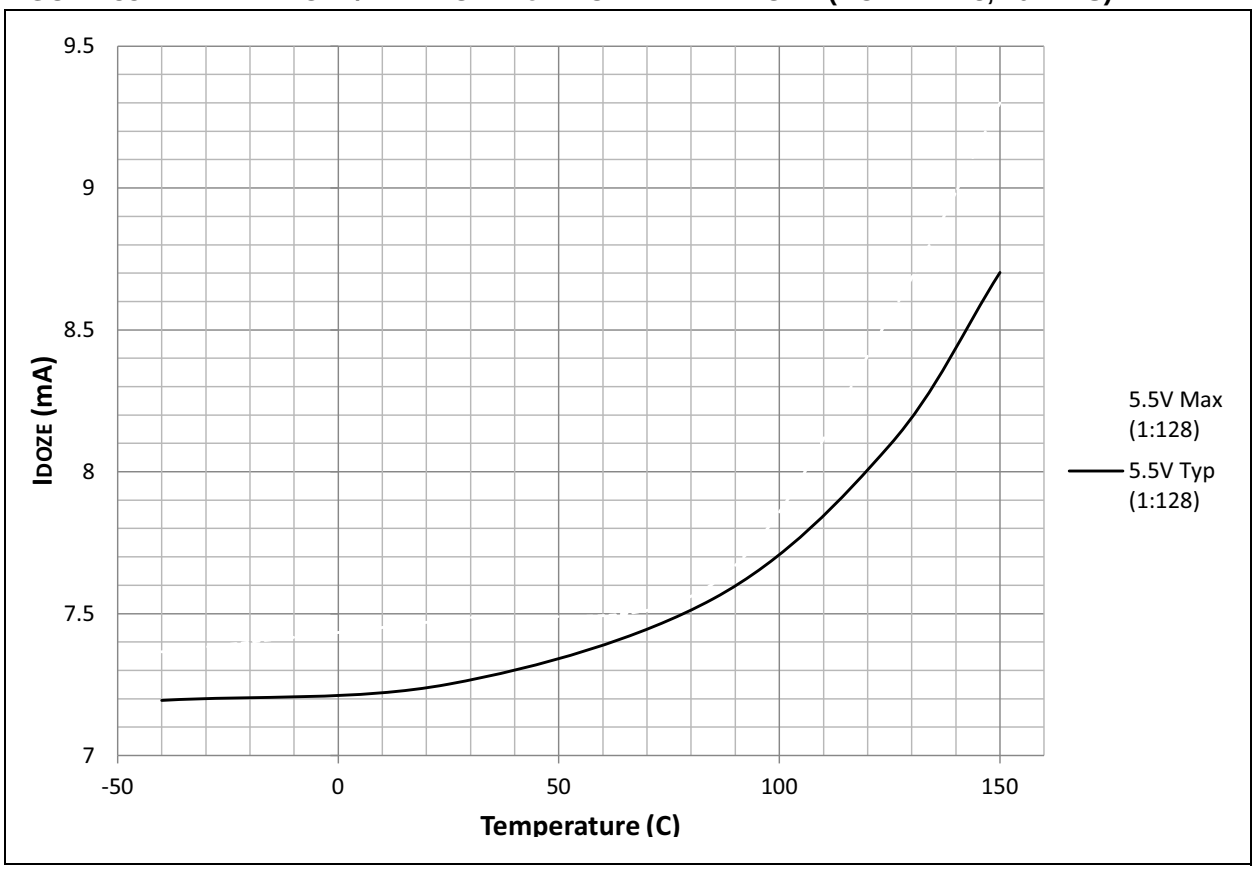
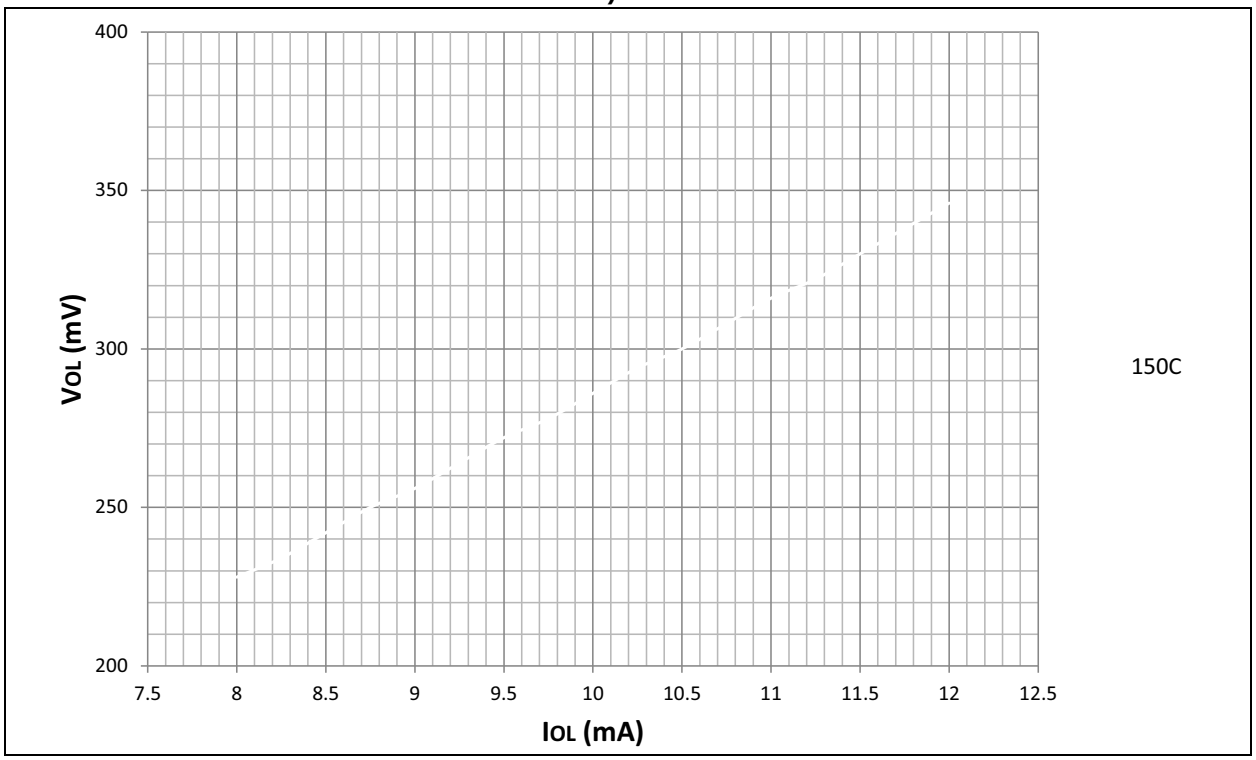
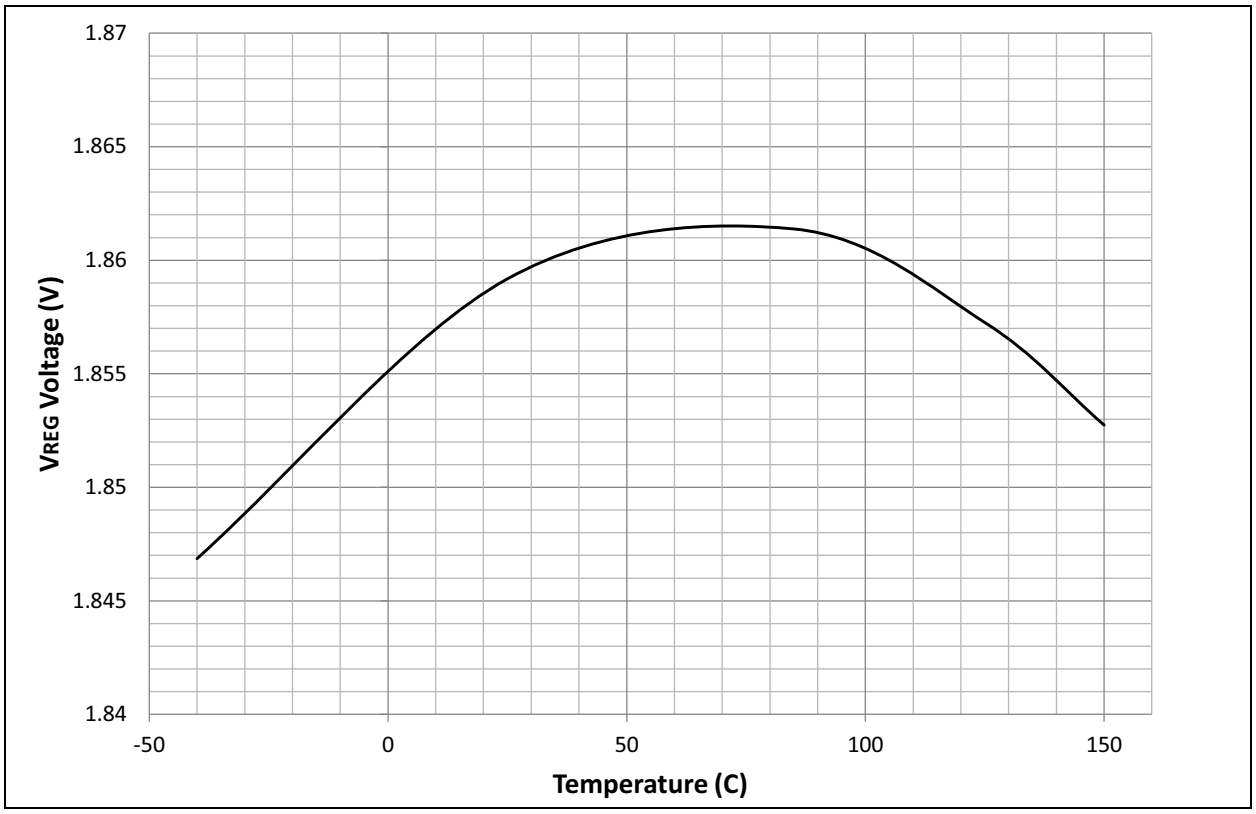


FIGURE 33-29: TYPICAL VOL 4x DRIVER PINS vs. IOL (GENERAL PURPOSE I/Os, TEMPERATURES AS NOTED)



33.11 VREG

FIGURE 33-30: TYPICAL REGULATOR VOLTAGE vs. TEMPERATURE

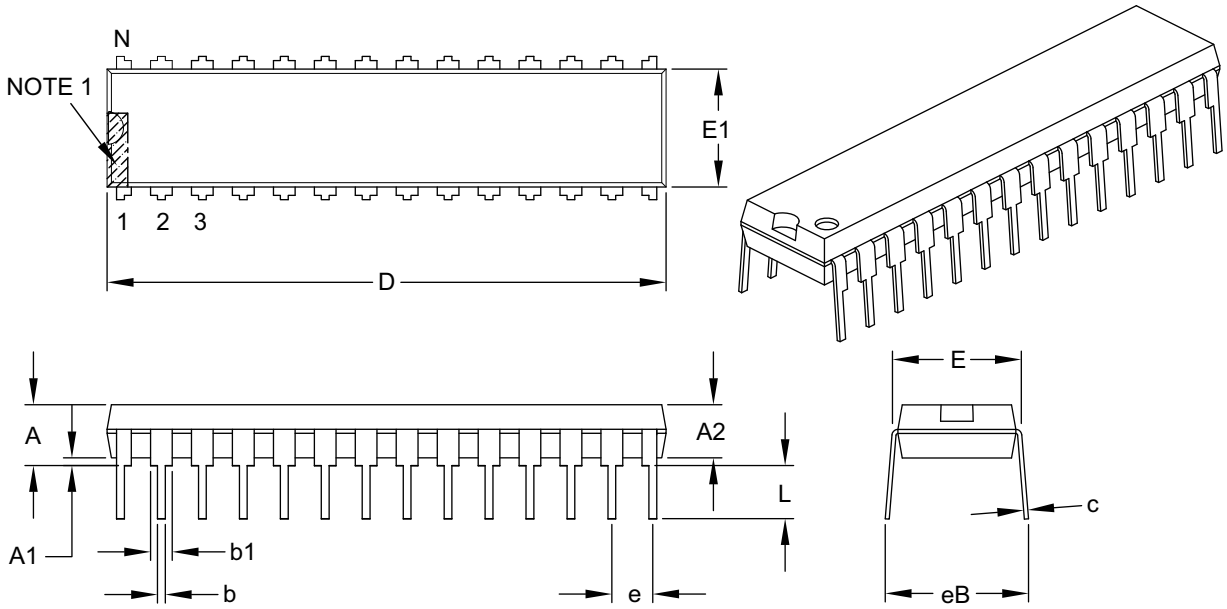


34.2 Package Details

The following sections give the technical details of the packages.

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B